materials

an Open Access Journal by MDPI

IMPACT FACTOR 3.1

Indexed in: PubMed

CITESCORE 5.8

# Advances in Electronics Packaging Materials and Technology

Guest Editor:

**Dr. Chang-Bun Yoon**
Department of Advanced Materials Engineering, Tech University of Korea, Siheung si 15073, Republic of Korea

Deadline for manuscript submissions:
**closed (20 July 2024)**

## Message from the Guest Editor

Dear Colleagues,

Packaging materials and technologies used in electronic products have continued to evolve with the advancement of science and technology. Electronic packaging includes various insulators, conductors, and polymer technologies to protect electronic products. With the recent emergence of mobile devices such as smartphones, packaging technology has been continuously developed to improve the reliability of manufacturing high-performance electronic products in a limited space. In the future, new technologies such as artificial intelligence, the Internet of Things, and robotics will help in developing ever more complex electronic products. Along with developing these products, electronic packaging technology is expected to develop further. Semiconductors show pattern accuracy at the 3nm level. Since high-performance semiconductor chips must be integrated into the limited space of a smartphone, related packaging technology has had to develop dramatically. In addition, in the case of secondary batteries, their use is expanding due to the rapid increase in electric vehicles.

mdpi.com/si/174843

# materials

an Open Access Journal by MDPI

IMPACT FACTOR 3.1

Indexed in: PubMed

CITESCORE 5.8

## Editor-in-Chief

**Prof. Dr. Maryam Tabrizian**
1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada
2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

## Message from the Editor-in-Chief

*Materials* (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

## Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.
**High Visibility:** indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.
**Journal Rank:** JCR - Q1 (Metallurgy and Metallurgical Engineering) / CiteScore - Q2 (*Condensed Matter Physics*)

## Contact Us

*Materials* Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
𝕏@Materials_Mdpi